



Electronic Filing System (EFS) Data
Electronic Patent Application Submission
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EFS ID: 58572
Application ID: 10605041
Title of Invention: METHOD OF FORMING A
THERMALLY CONDUCTIVE
ARTICLE USING METAL
INJECTION
First Named Inventor: Kevin McCULLOUGH
Domestic/Foreign Application: Domestic Application
Filing Date: 2003-09-03
Effective Receipt Date: 2004-04-07
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Statement
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Confirmation number: 2040
Attorney Docket Number: C001CPP00404US2




Total Fees Authorized:

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TRANSMITTAL

Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention	METHOD OF FORMING A THERMALLY CONDUCTIVE ARTICLE USING METAL INJECTION									
Application Number: 10/605041 										
Date: 2003-09-03										
First Named Applicant: Mr. Kevin A. McCULLOUGH										
Confirmation Number: 2040										
Attorney Docket Number: C001CPP00404US2										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mr. David R. Josephs Registered Number: 34,632</td><td>/david r. josephs/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mr. David R. Josephs Registered Number: 34,632	/david r. josephs/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
Mr. David R. Josephs Registered Number: 34,632	/david r. josephs/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>P00404US2A-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	P00404US2A-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	P00404US2A-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

METHOD OF FORMING A THERMALLY CONDUCTIVE
ARTICLE USING METAL INJECTION

Application Number: 10/605041



Confirmation Number: 2040

First Named Applicant: Kevin McCULLOUGH

Attorney Docket Number: C001CPP00404US2

Art Unit: 1775

Search string: (T904012 or 3398322 or 3673121 or 3708387
or 40998945 or 4307147 or 4367745 or
4496475 or 4568592 or 4664971 or 4689250 or
4816184 or 5011870 or 5011872 or 5021494 or
5098610 or 5106540 or 5180513 or 5213715 or
5225110 or 5286416 or 5302456 or 5334330 or
5373046 or 5397608 or 5445308 or 5490319 or
5522962 or 5536568 or 5580493 or 5669381 or
5681883 or 5770305 or 5834337 or 5851644 or
5863467 or 5945217 or 6048919 or 4470063 or
5037590 or 5373046 or 5400505 or 5454425 or
5552214 or 5660923 or 5981085 or 6139783 or
6303096 or 20020022686 or 20020025998).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	T904012	1972-11-07	Staniland		252	503
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	3	3673121	1972-06-27	Meyer		252	511
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428	288
427	216
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Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
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	2	20020025998	2002-02-28	McCullough et al.	A1	524	66

Signature

Examiner Name	Date